

NTS062P03S8



P-Channel Enhancement Mode Trench Power MOSFET

Voltage: -30 Volts

Current: -15 Amperes

Package: SOP-8

Features

- NH'S Advanced Trench Technology
- Low Rds(on) For Low On-State Loss
- High EAS For High Reliability
- Excellent Qg*Rds(on) Product(FOM)

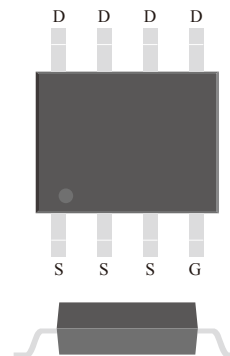
Typical Applications

- DC-DC Converter
- Battery Management System(BMS)
- Printed Circuit Board For Control Circuit
- Uninterruptible Power Supplies(UPS)

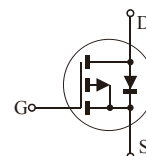
Product Summary

VDS Min.@Tj	-30	V
ID Min.@Ta	-15	A
RDS(ON)(TYP)@-10V	6	mΩ

Diagram:



Polarity:



***100% UIS TESTED**

***100% ΔVDS TESTED**

Absolute Maximum Ratings (Ta=25℃ Unless Otherwise Specified)

Parameter	Test Conditions	Symbol	Ratings	Unit
Drain-Source Voltage		V _{DS}	-30	V
Gate-Source Voltage		V _{GS}	±20	V
Continuous Drain Current (Note 1)	Ta= 25 ℃	I _D	-15	A
	Ta= 100 ℃		-10	
Drain Current-Pulse (Note 1)	Tj< 150 ℃	I _{DM}	-60	A
Maximum Power Dissipation Power Dissipation Derating Factor Above 25℃	Ta= 25 ℃	P _D	6	W
	Ta= 100 ℃		3	
Derating Factor		D _F	0.05	W/℃
Avalanche Current,Single Pulse (Note 1)	L= 0.5 mH	I _{AS}	-23	A
Single Pulse Avalanche Energy (Note 1) Test Circuit & Waveform See Fig.17	L= 0.5 mH IAS= -23 A,RG= 10.0 Ω Starting Tj=25 ℃,VG = 10 V	E _{AS}	132	mJ

Thermal Characteristics (Ta=25℃ Unless Otherwise Specified)

Parameter	Test Conditions	Symbol	Typ.	Unit
Junction Temperature		T _J	-55 to 150	℃
Storage Temperature Range		T _{STD}	-55 to 150	℃
Thermal Resistance Junction To Ambient With Steady-State	Still Air Environment With Ta=25℃	R _{θJA}	50	℃/W
Thermal Resistance Junction-Case With Steady-State	Device Mounted On 1 in2 FR-4 Board With 2oz. Copper	R _{θJC}	20	

Notes: 1.Pulse Width Limited By Max. Junction Temperature. (See Fig.14)

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Electrical Characteristics (Ta=25°C Unless Otherwise Specified)

Parameter	Test Conditions	Symbol	Min.	Typ.	Max.	Unit
Static Off Characteristics						
Drain-Source Breakdown Voltage	VGS=0V,ID=250uA	BV _{DSS}	-30	--	--	V
Bvdss Temperature Coefficient	ID=250uA,Reference25℃	ΔBV _{DSS} /ΔT _J	--	0.03	--	V/℃
Drain-Source Leakage Current	VDS= -30 V,VGS=0V	I _{DSS}	--	--	-1	uA
Gate-Body Leakage Current	VGS= ±20 V,VDS=0V	I _{GSS}	--	--	±100	nA
Forward Transconductance	ID= -7.5 A,VDS= -5 V	g _{fs}	--	35	--	S
Static On Characteristics						
Gate Threshold Voltage	VGS= VDS ID=-250uA	V _{GS(TH)}	-1	-1.8	-2.5	V
Drain-Source On Resistance	ID= -7.5 A,VGS= -10.0 V	R _{DS(ON)}	--	6.2	10	mΩ
	ID= -7.5 A,VGS= -5.0 V		--	9	15	
Dynamic Characteristics						
Gate Resistance	VGS=0V,VDS=0V, Freq.=1MHz	R _g	--	10	--	Ω
Input Capacitance	VDS= -15 V VGS= 0 V F= 1 MHZ	C _{iss}	--	2760	--	pF
Output Capacitance		C _{oss}	--	320	--	pF
Reverse Transfer Capacitance		C _{rss}	--	290	--	pF
Switching Paramters With Inductive Load(Test Circuit & Waveform See Fig.15)						
Turn-On Delay Time	VDS= -15 V VGS= -10.0 V RG= 10.0 Ω L= 0.5 mH	t _{d(on)}	--	18	--	ns
Turn-On Rise Time		t _r	--	22	--	ns
Turn-Off Delay Time		t _{d(off)}	--	55	--	ns
Turn-Off Rise Time		t _f	--	40	--	ns
Gate Charge Paramters (Test Circuit & Waveform See Fig.16)						
Total Gate Charge	VDS= -15 V VGS= -10.0 V ID= -15.0 A	Q _g	--	53	--	nC
Gate-Source Charge		Q _{gs}	--	12	--	nC
Gate-Drain Charge		Q _{gd}	--	9	--	nC
Drain-Source Diode Characteristics And Maximum Ratings (Test Circuit & Waveform See Fig.18)						
Max. Diode Forward Current		I _S	--	--	-15.0	A
Max. Pulsed Forward Current		I _{SM}	--	--	-60	A
Diode Forward Voltage	ID= -7.5 A,VGS=0V	V _{SD}	--	-0.7	-1.2	V

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Typical Characteristics Curves

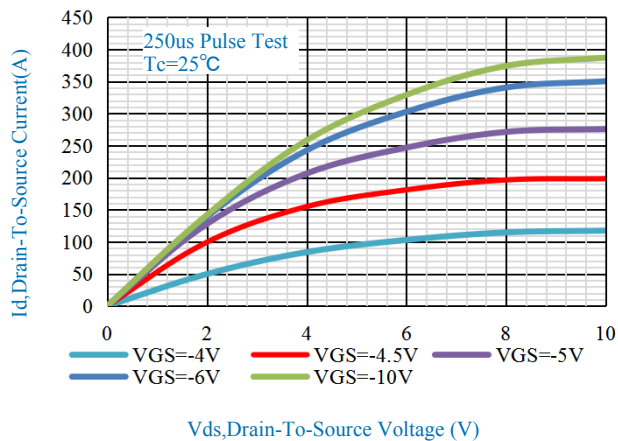


Fig.1-Output Characteristic

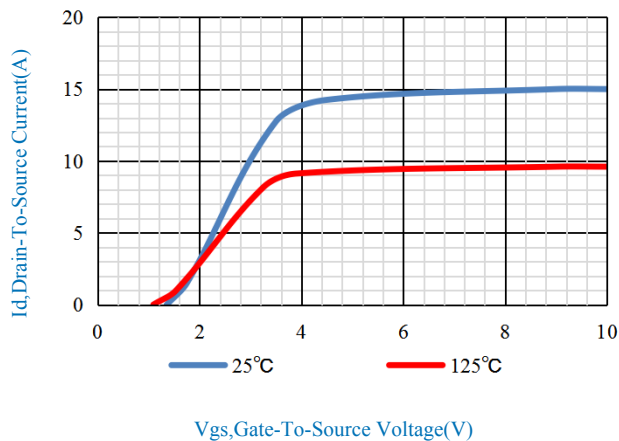


Fig.2-Transfer Characteristic

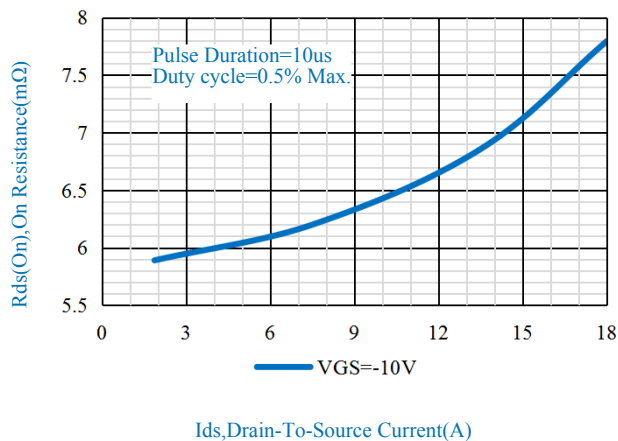


Fig.3-On Resistance Vs. Drain Current

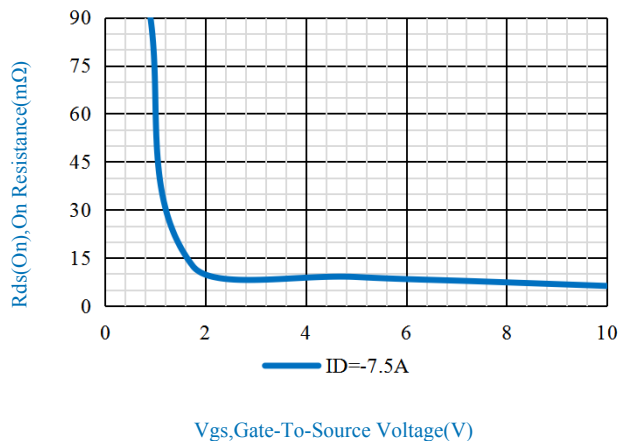


Fig.4-On Resistance Vs. Gate Source Voltage

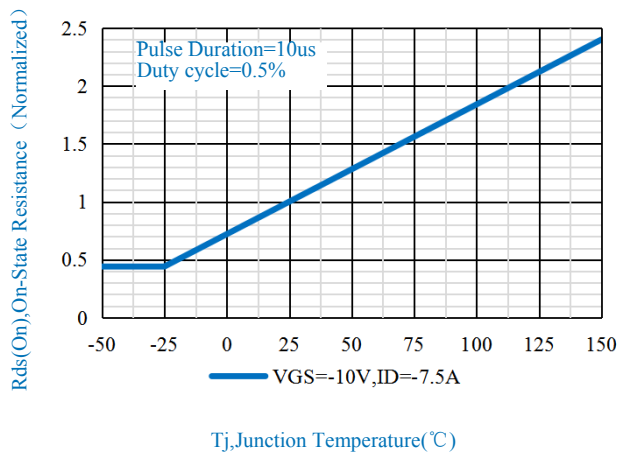


Fig.5-On Resistance Vs. Junction Temperature

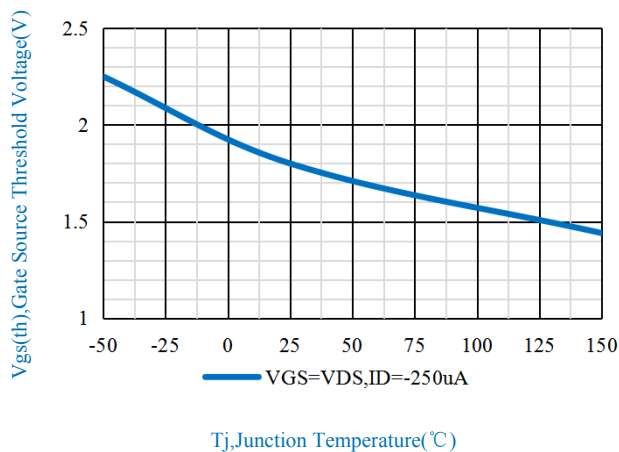


Fig.6-Gate Source Threshold Voltage Vs. Junction Temperature

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Typical Characteristics Curves

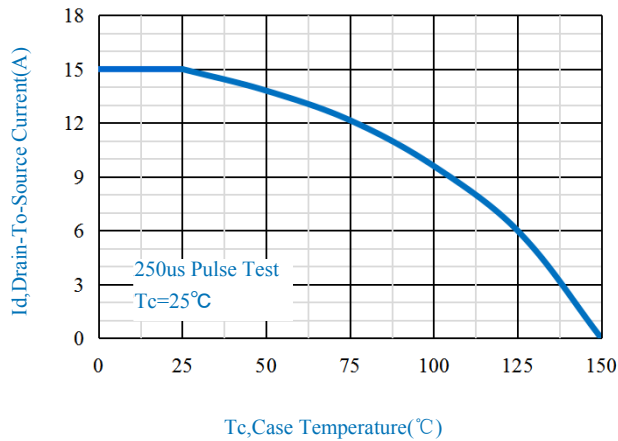


Fig.7-Maximum Continuous Drain Current Vs. Case Temperature

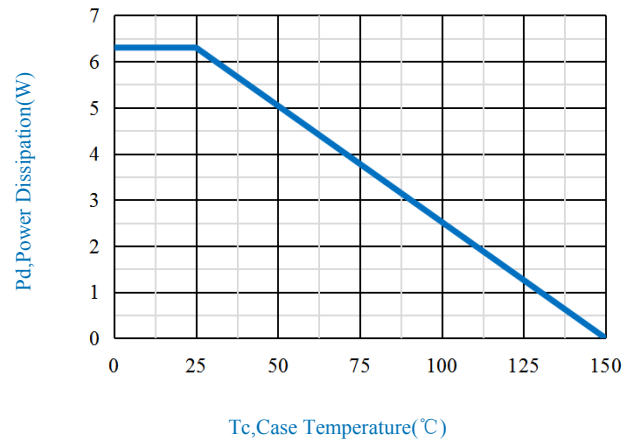


Fig.8-Maximum Power Dissipation Vs. Case Temperature

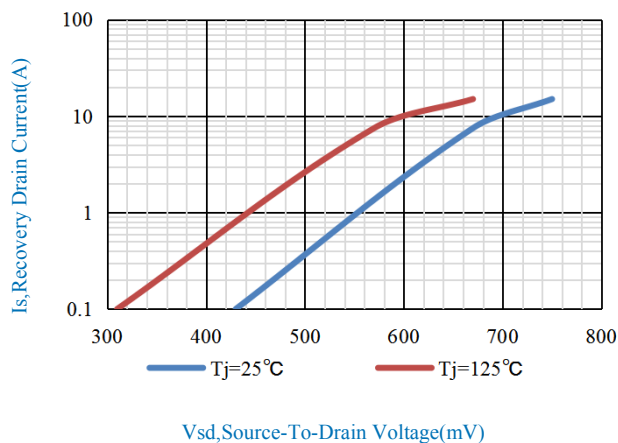


Fig.9-Source-To-Drain Diode Forward Voltage

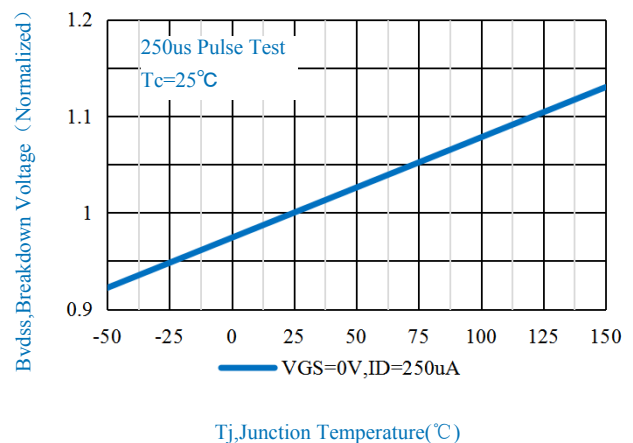


Fig.10-Breakdown Voltage Vs. Junction Temperature

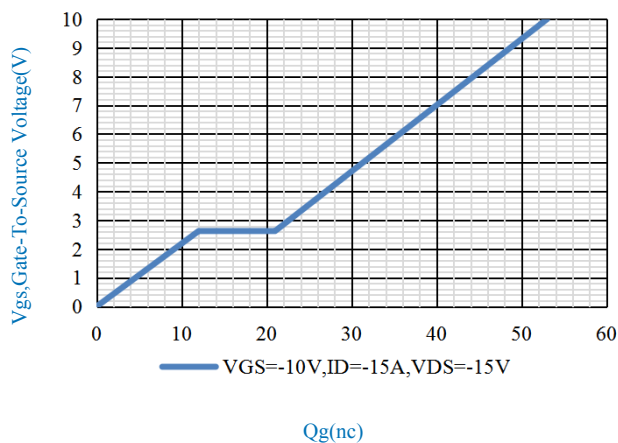


Fig.11-Gate Charge Waveform

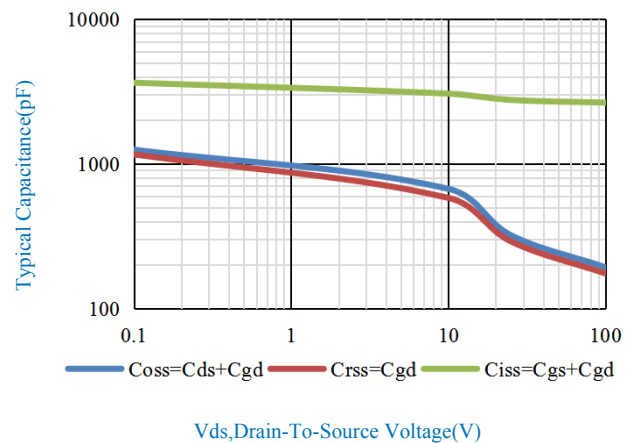


Fig.12-Typical Capacitance Vs. Drain-To-Source Voltage

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Typical Characteristics Curves

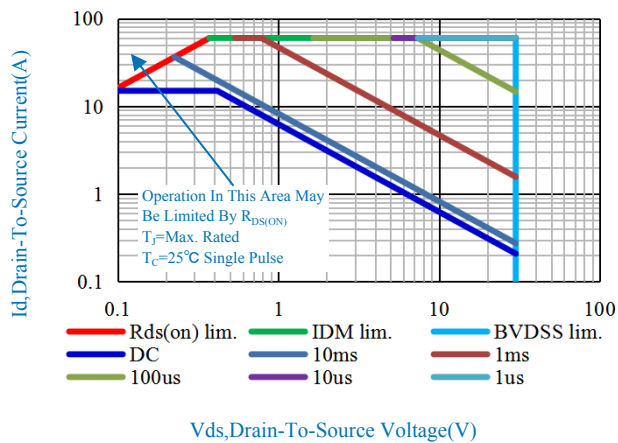


Fig.13-Maximum Safe Operating Area(SOA)

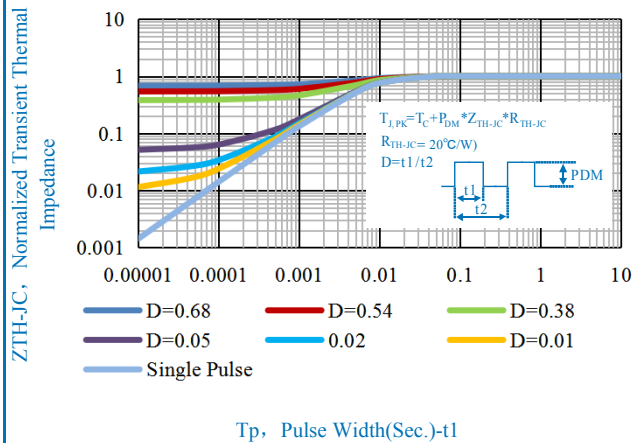


Fig.14- Normalized Maximum Transient Thermal Impedance Vs. Pulse Width

Inductive Load Test Circuit & Waveform

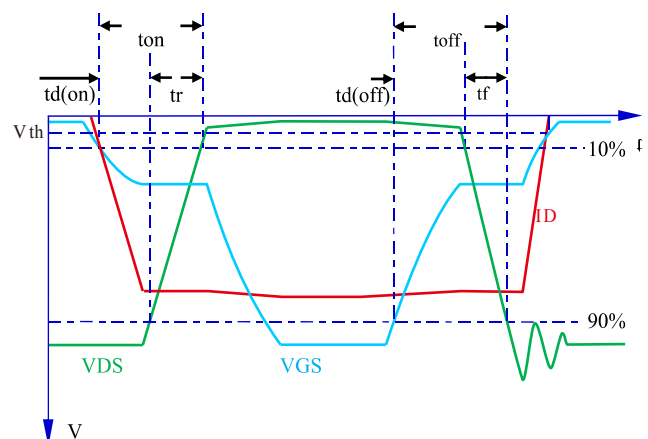
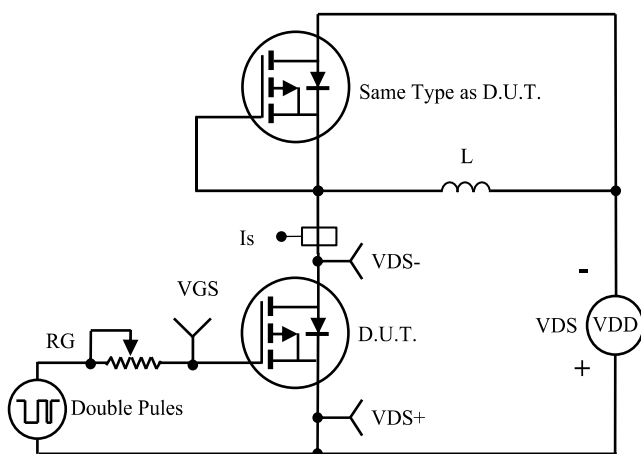


Fig.15- Inductive Switching Test Circuit & Waveform

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Test Circuit & Waveform

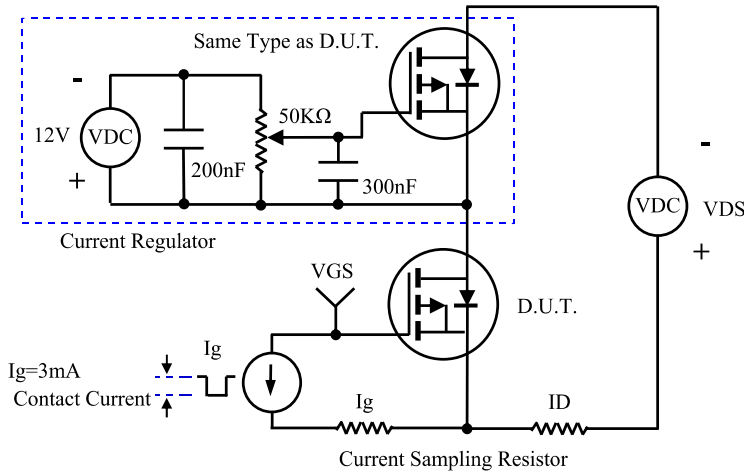


Fig.16-Gate Charge Test Circuit & Waveform

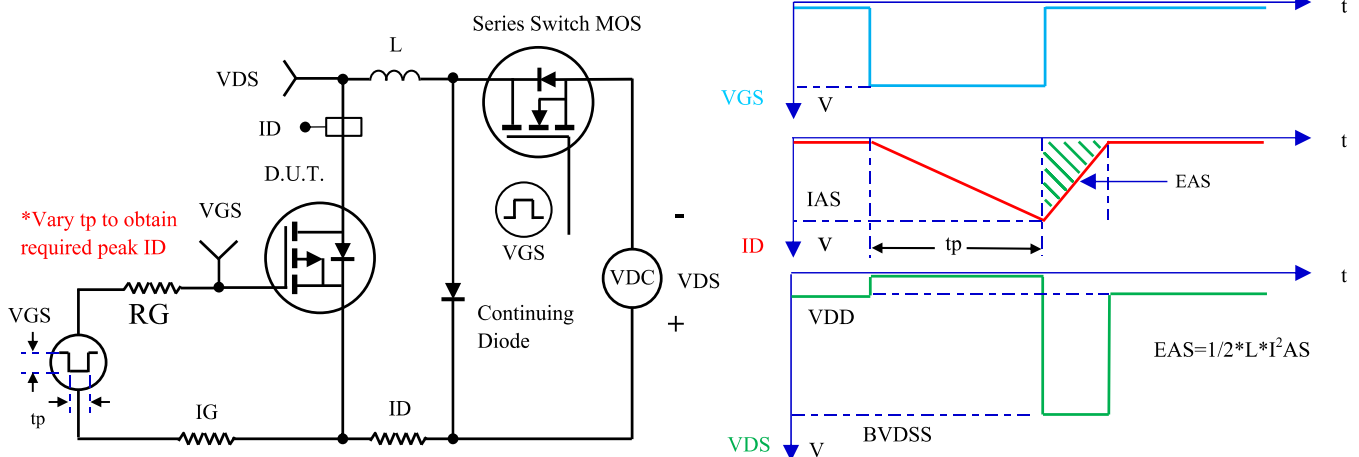


Fig.17- Unclamped Inductive Switching (UIS) Test Circuit & Waveform

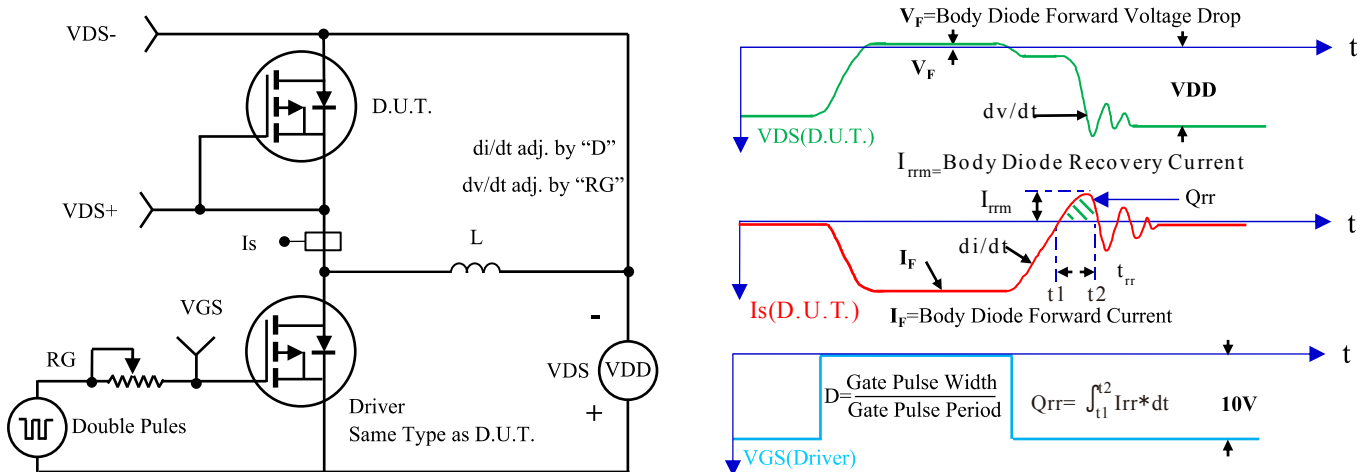


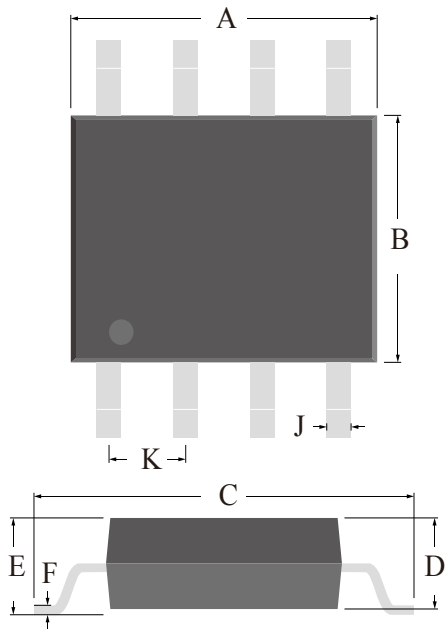
Fig.18- Diode Recovery Test Circuit & Waveform

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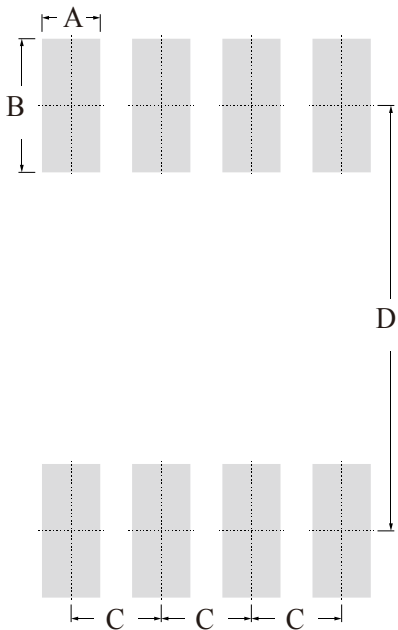
OUTLINE DRAWINGS



SOP-8

OUTLINE DIMENSIONS						
Dim.	Milimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.70	-	5.30	0.1850	-	0.2087
B	3.65	-	4.05	0.1437	-	0.1594
C	5.70	-	6.70	0.2244	-	0.2638
D	1.22	-	1.62	0.0480	-	0.0638
E	1.31	-	1.71	0.0516	-	0.0673
F	0.10	-	0.30	0.0039	-	0.0118
J	0.25	-	0.55	0.0098	-	0.0217
K	1.05	-	1.45	0.0413	-	0.0571

RECOMMEDND LAYOUT DRAWINGS



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OUTLINE DIMENSIONS						
Dim.	Milimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	-	0.80	-	-	0.0315	-
B	-	1.75	-	-	0.0689	-
C	-	1.25	-	-	0.0492	-
D	-	7.35	-	-	0.2894	-

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MARKING INFORMATION



MARKING INSTRUCTIONS

NH=Niuhang Trademark
FF=Product Line Code,According To Actual Changes
YWW=Date Code,According To Actual Changes
LLWWF=Inernal Code,According To Actual Changes
NTS062P03S8=Model

PACKING INFORMATION

Package Type	Package Code	Product Weight Approx(g/Pcs)	Package Method	Quantity (Pcs/Min. Pack.)	Quantity (Pcs/Inner Box)	Quantity (Pcs/Carton)
SOP-8	P1	0.173	13" Reel	3000	6000	48000

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Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

Recommended temperature profile for IR reflow

	Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
	Average ramp-up rate (T _{smax} to T _p)	3°C/second max.	3°C/second max.
	Preheat-Temperature Min (T _S min) -Temperature Max (T _S max) -Time(t _s min to t _s max)	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds
	Time maintained above: -Temperature (T _L) - Time (t _L)	183°C 60-150 seconds	217°C 60-150 seconds
	Peak Temperature(T _P)	240 +0/-5 °C	260 +0/-5 °C
	Time within 5°C of actual peak temperature (t _p)	10-30 seconds	20-40 seconds
	Ramp down rate	6°C/second max.	6°C/second max.
	Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

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Specification Revision History

Rev.	Date	Changed Items	Pre-Changed Content	Changed Content
A/1	2014-10-20	First Issue		
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